



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-01-08
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STL260N45LF7	BXER*OLD8R82	A	3068	2019-01-08
Amount	UoM	Unit type	ST ECOPACK Grade	
100.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5-6-0.8	12	Flat	
Comment	Power FLAT 5x6 8L SINGLE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.10	Die	1000
Lead	8.23	Soft solder	82290

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	8.23	Soft solder	82290
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	8.23	Soft solder	925022

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BXER*OLDR82					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.903	mg	supplier	die	Silicon (Si)	7440-21-3		2.483	mg	855322	24830
				supplier	metallization	Aluminium (Al)	7429-90-5		0.164	mg	56493	1640
				supplier	metallization	Nickel (Ni)	7440-02-0		0.041	mg	14123	410
				supplier	metallization	Silver (Ag)	7440-22-4		0.024	mg	8269	240
				supplier	metallization	Titanium (Ti)	7440-32-6		0.018	mg	6200	180
				supplier	metallization	Tungsten (W)	7440-33-7		0.041	mg	14123	410
				supplier	Passivation	Silicon Oxide	7631-86-9		0.040	mg	13779	400
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.005	mg	1722	50
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.059	mg	20324	590
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.004	mg	1378	40
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.024	mg	8267	240
				supplier	alloy	Copper (Cu)	7440-50-8		47.330	mg	984196	473300
				Leadframe	M-004 Copper and its alloys	48.090	mg	supplier	alloy	Iron (Fe)	7439-89-6	
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.014	mg	292	140
supplier	metallization	Silver (Ag)	7440-22-4						0.699	mg	14535	6990
JIG - R	solder	Lead (Pb)	7439-92-1					7a-Lead in high mel	8.229	mg	925022	82290
supplier	solder	Tin (Sn)	7440-31-5						0.222	mg	24955	2220
Soft solder	Solder	8.896	mg	supplier	solder	Silver (Ag)	7440-22-4		0.445	mg	50023	4450
				supplier	wire	Gold (Au)	7440-57-5		0.116	mg	1000000	1160
				supplier	mold compound	Silica, vitreous	60676-86-0		29.032	mg	924236	290321
Bonding wires	M-011 Other inorganic materials	0.116	mg	supplier	mold compound	epoxy resin	85954-11-6		1.285	mg	40892	12845
				supplier	mold compound	phenol resin	26834-02-6		0.965	mg	30721	9650
				supplier	mold compound	carbon black	1333-86-4		0.130	mg	4151	1304
Encapsulation	M-011 Other inorganic materials	31.412	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	1490
Connections coating	Solder	0.149	mg	supplier	alloy	Copper (Cu)	7440-50-8		8.434	mg	1000000	84340
Clip	M-004 Copper and its alloys	8.434	mg	supplier	alloy	Copper (Cu)	7440-50-8		8.434	mg	1000000	84340